ABSTRACT

METHOD OF SEMICONDUCTOR MANUFACTURE

A method for rerouting a bond pad on a semiconductor wafer which avoids the sputtering process. Various chemical-based processes are used to provide that the effective position of the bond pad is changed. In particular, the method comprises depositing nickel on said bond pad using an electroless method, depositing a layer of dielectric on the nickel and passivation, patterning the dielectric to reveal the nickel, depositing copper on the nickel using a combination of electroless and electrolytic methods, depositing a photoresist layer on the copper layer, etching this to leave a copper re-route, applying a layer of passivation, forming a hole in the layer of passivation to expose part of the copper reroute, plating this exposed part with nickel or gold, depositing solder on this plated part and heating the solder to reflow it into a more appropriate shape.

Figure 2